

WHAT IS CLAIMED IS:

1. A method for applying solder mask onto solder pad spacings on a printed circuit board, characterized in that, an ink-jet printer is employed to print solder mask onto solder pad spacings on a printed circuit board.
2. The method for applying solder mask onto solder pad spacings on a printed circuit board as in claim 1, wherein the central spacings of said solder pads are smaller than or equal to 0.5 mm.
3. The method for applying solder mask onto solder pad spacings on a printed circuit board as in claim 1, wherein the width of said solder mask is no wider than 150 μ m.
4. The method for applying solder mask onto solder pad spacings on a printed circuit board as in claim 1, wherein the thickness of said solder mask is no thicker than 55 μ m.
5. The method for applying solder mask onto solder pad spacings on a printed circuit board as in claim 1, wherein the primary material for said solder mask can be epoxy resin series, acrylic resin series or the mixture of epoxy resin series and acrylic resin series.

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